
**PRODUCT/PROCESS
CHANGE NOTIFICATION**

PCN APMS/25/15686

Analog, Power, MEMS & Sensors (APMS)

**ST Manufacturing Reshaping (Analog_FE+EWS BCD9 AG200toAG300_all):
Qualification of ST Agrate 12 inches (Italy) as new FE location and ST Crolles
(France) as new EWS Location for BCD9 products**

Issue date: 30th July 2026

Description of the change

Following Corporate PCI 15383 (Early Notification), about Company reshaping program, please be informed that EWS (Electrical Wafer Sorting) of Analog products listed here below will be transferred from ST Agrate (Italy) to ST Crolles (France).

Change Summary:

	Former	New
EWS/Location	ST Agrate	ST Crolles

Traceability:

Internal Traceability – Date code-
Step tracked in ST production systems and available real time on demand

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Affected products

Refer to Below table for involved Commercial Products.

Specific devices not expressly listed in this table are included in this change.

CP code involved in qualification		
L9026-B03N-TR	L9963E	L99DZ300-TR
L9026-YO-TR	L9963E-TR	L99DZ320TR
L9600	L9963-TR	L99LDLH32TR
L9600-TR-TX	L9965A-TR	L99PCUFA
L9601	L99BM114	L99PCUFAG
L9601-TR	L99BM114-TR	L99PCUFAG-TR
L9783-TR	L99BM218-TR	L99PCUFA-TR
L9784	L99DZ300	MAR9770L
L9785	L99DZ300GTR	MAR9770LTR
L9788A-TR	L99DZ300H	STSPIN32G4
L9963	L99DZ300HTR	STSPIN32G4TR

Dual die (one of the dice qualified)
Qualification on going
Qualified

Reason

Die manufacturing: ST manufacturing reshaping program - Corporate PCI - Early Notification.

Date of implementation

First shipments forecast: one month after Qualification completion date (see below qualification results date for reference).

Impact of change

Form	Not Impacted
Fit	Not Impacted
Function	Not Impacted
Reliability	Not Impacted
Processibility	Not Impacted

Qualification of the change (plan)

Qualification will be performed according to ST guidelines and ZVEI (ID SEM-TF01) for Automotive products.

Compliant with ST internal spec and ZVEI Guideline Product and Process Changes (PCN) 5.0 (Automotive products)				
		Line readiness	ED (Electrical Distribution, Cpk, analysis *)	Parametric analysis (Yield, Bin to Bin *)
Product		•	•	•

* Comparing wafers in old vs. new location

Disposition of former products

Delivery of current products will be done until stock depletion.

Qualification results

Qualification report including qualification results is enclosed at the end of this document:

Qualification completion date: April-2026.

Sampling plan

Customer samples are not planned; the switch of production will occur at product validation.

Qualification Report

Transfer of EWS (Electrical Wafer Sorting) from ST Agrate (Italy) to ST Crolles (France) for Analog products

General Information	
Commercial Product	See above list
Product perimeter	Analog
Product group	APMS
Maturity level	Qualified

Locations	
Diffusion Plant	Multiple
Assembly Plant	Multiple
Reliability Lab	N/A

Assessment	
Pass	X
Fail	

Table of contents

1.	APPLICABLE AND REFERENCE DOCUMENTS.....	6
2.	GLOSSARY	6
3.	RELIABILITY EVALUATION OVERVIEW	6
3.1.	Objective	6
3.2.	Conclusion	6
4.	PRODUCT OR TEST VEHICLE CHARACTERISTICS.....	7
4.1.	Device description.....	7
4.2.	Package Outline.....	Error! Bookmark not defined.
4.3.	Construction note	8
5.	TEST RESULTS SUMMARY	9
5.1.	Lot information	9
5.2.	Test plan and results summary.....	9
6.	APPLICABLE AND REFERENCE DOCUMENTS.....	Error! Bookmark not defined.
7.	TESTS DESCRIPTION.....	Error! Bookmark not defined.

1. APPLICABLE AND REFERENCE DOCUMENTS

ZVEI	Change Standard Methodology
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2. GLOSSARY

EWS	Electrical Wafer Sorting
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3. RELIABILITY EVALUATION OVERVIEW

3.1. Objective

The objective of this report is to qualify the transfer of EWS (Electrical Wafer Sorting) from ST Catania (Italy) to ST Crolles for products detailed in PCN: Qualification plan conducted following ZVEI matrix as follow:

	ZVEI DEFAULT	ZVEI WITH CONDITIONS	ST SELECTED	REASON FOR EXCEPTION OF TESTS
AEC-Q101 Revision E	•	•	X	
Parametric Verification	•	•	X	No characterization planned as only EWS is transferred*
Parameter-Analysis: Comparison of current with changed device characterization, electrical distribution	•	•	X	

*Characterization is meant for Final Test transfer, not applicable for this EWS transfer

3.2. Conclusion

Qualification Plan requirements have been fulfilled without exception. Line readiness tests, Electrical Distribution, Cpk, Yield and Bin to Bin analysis and comparison have all shown positive results. Based on these results, all devices are ready for the EWS transfer from ST Agrate to ST Singapore.

4. PRODUCT OR TEST VEHICLE CHARACTERISTICS

4.1. Device description

Refer to ST specification:

4.2. Construction note

All parts listed in page 6	
Wafer/Die fab. information	
Wafer fab manufacturing location	multiple
Technology	multiple
Wafer Testing (EWS) information	
Electrical testing manufacturing location	ST Crolles

5. TEST RESULTS SUMMARY

5.1. Lot information

Lot #	Part Number	Comment
Lot 1	L9026-B03N-TR	
Lot 2	L9963E-TR	
Lot 3	L9963-TR	
Lot 4	L9963E-TR	
Lot 5	L9601-TR	
Lot 6	L9783-TR	

Detailed results in below chapter will refer to these references.

5.2. Test plan

Qualification of the change (plan)			
Qualification will be performed according to and ST guidelines and ZVEI (ID SEM-TF01) for Automotive products.			
Compliant with ST internal spec and ZVEI Guideline Product and Process Changes (PCN) 5.0 (Automotive products)			
	Line readiness	ED (Electrical Distribution, Cpk, analysis *)	Parametric analysis (Yield, Bin to Bin *)
Product	*	*	*

*comparing wafers in ol vs. new location

5.3. results summary

Item	Qualification activity	Sample size	L9026-B03N-TR	L9963E-TR	L9963-TR	L9963E-TR	L9601-TR	L9783-TR
EWS line transfer	Line readiness	1 lot	PASS	PASS	PASS	PASS	PASS	PASS
	ED (Electrical Distribution, Cpk analysis)	1 full wafers	PASS	PASS	PASS	PASS	PASS	PASS
	Parametric analysis (Yield, Bin to Bin)	1 full wafers	PASS	PASS	PASS	PASS	PASS	PASS

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